

The RF MOSFET Line

RF Power Field Effect Transistors

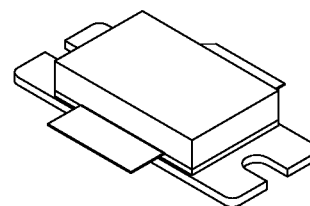
N-Channel Enhancement-Mode Lateral MOSFETs

Designed for GSM and EDGE base station applications from frequencies up to 1.8 to 2.0 GHz. Suitable for FM, TDMA, CDMA and multicarrier amplifier applications. To be used in class AB for GSM and EDGE cellular radio applications.

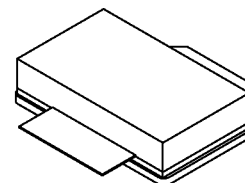
- GSM and EDGE Performances, Full Frequency Band
Power Gain — 13.5 dB (Typ) @ 90 Watts (CW)
Efficiency — 52% (Typ) @ 90 Watts (CW)
- Internally Matched, Controlled Q, for Ease of Use
- High Gain, High Efficiency and High Linearity
- Integrated ESD Protection: Class 2 Human Body Model, Class M3 Machine Model
- Ease of Design for Gain and Insertion Phase Flatness
- Capable of Handling 10:1 VSWR, @ 26 Vdc, 90 Watts (CW) Output Power
- Excellent Thermal Stability
- Characterized with Series Equivalent Large-Signal Impedance Parameters

MRF18090A
MRF18090AS

90 W, 1.80 – 1.88 GHz, 26 V
LATERAL N-CHANNEL
BROADBAND
RF POWER MOSFETS



CASE 465B-02, STYLE 1



CASE 465C-01, STYLE 1

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	65	Vdc
Gate-Source Voltage	V_{GS}	+15, -0.5	Vdc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	250 1.43	Watts W/ $^\circ\text{C}$
Storage Temperature Range	T_{stg}	-65 to +200	$^\circ\text{C}$
Operating Junction Temperature	T_J	200	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	0.7	$^\circ\text{C/W}$

NOTE – **CAUTION** – MOS devices are susceptible to damage from electrostatic charge. Reasonable precautions in handling and packaging MOS devices should be observed.

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain–Source Breakdown Voltage ($V_{GS} = 0\text{ Vdc}$, $I_D = 100\text{ }\mu\text{Adc}$)	$V_{(BR)DSS}$	65	—	—	Vdc
Zero Gate Voltage Drain Current ($V_{DS} = 26\text{ Vdc}$, $V_{GS} = 0$)	I_{DSS}	—	—	10	μAdc
Gate–Source Leakage Current ($V_{GS} = 5\text{ Vdc}$, $V_{DS} = 0$)	I_{GSS}	—	—	1	μAdc

ON CHARACTERISTICS

Gate Quiescent Voltage ($V_{DS} = 26\text{ Vdc}$, $I_D = 750\text{ mAdc}$)	$V_{GS(Q)}$	2.5	3.7	4.5	Vdc
Drain–Source On–Voltage ($V_{GS} = 10\text{ Vdc}$, $I_D = 1\text{ Adc}$)	$V_{DS(on)}$	—	0.1	—	Vdc
Forward Transconductance ($V_{DS} = 10\text{ Vdc}$, $I_D = 3\text{ Adc}$)	g_{fs}	—	7.2	—	S

DYNAMIC CHARACTERISTICS

Reverse Transfer Capacitance ($V_{DS} = 26\text{ Vdc}$, $V_{GS} = 0$, $f = 1\text{ MHz}$)	C_{rss}	—	4.2	—	pF
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FUNCTIONAL TESTS (In Motorola Test Fixture)

Common–Source Amplifier Power Gain @ 90 W (1) ($V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 750\text{ mA}$, $f = 1805 - 1880\text{ MHz}$)	G_{ps}	12.0	13.5	—	dB
Drain Efficiency @ 90 W (1) ($V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 750\text{ mA}$, $f = 1805 - 1880\text{ MHz}$)	η	47	52	—	%
Input Return Loss (1) ($V_{DD} = 26\text{ Vdc}$, $P_{out} = 90\text{ W CW}$, $I_{DQ} = 750\text{ mA}$, $f = 1805 - 1880\text{ MHz}$)	IRL	10	—	—	dB
Output Mismatch Stress ($V_{DD} = 26\text{ Vdc}$, $P_{out} = 90\text{ W CW}$, $I_{DQ} = 750\text{ mA}$ VSWR = 10:1, All Phase Angles at Frequency of Tests)	Ψ	No Degradation In Output Power Before and After Test			

(1) To meet application requirements, Motorola test fixtures have been designed to cover the full GSM1800 band, ensuring batch–to–batch consistency.

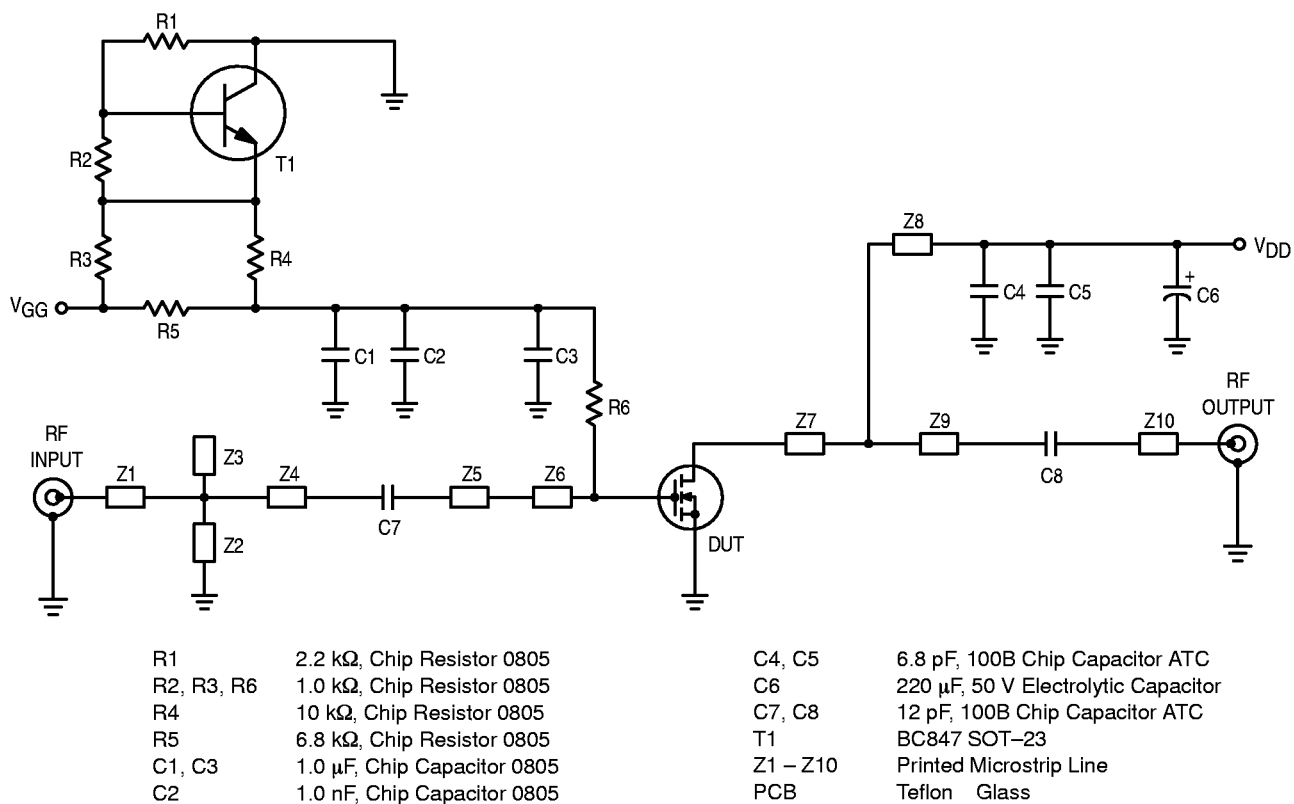


Figure 1. 1.80 – 1.88 GHz Test Fixture Schematic

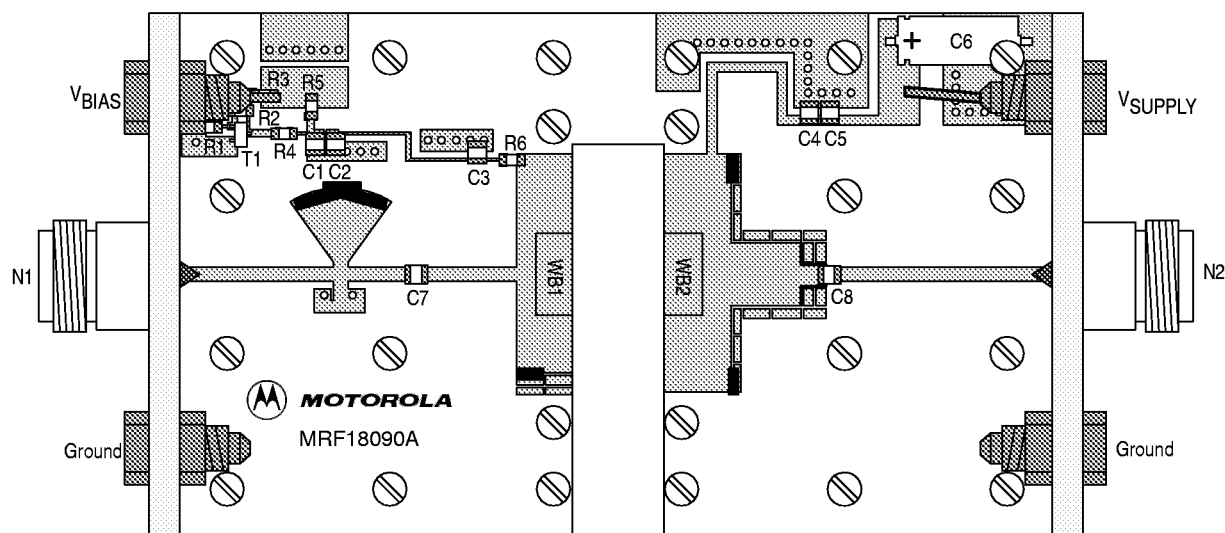


Figure 2. 1.80 – 1.88 GHz Test Fixture Component Layout

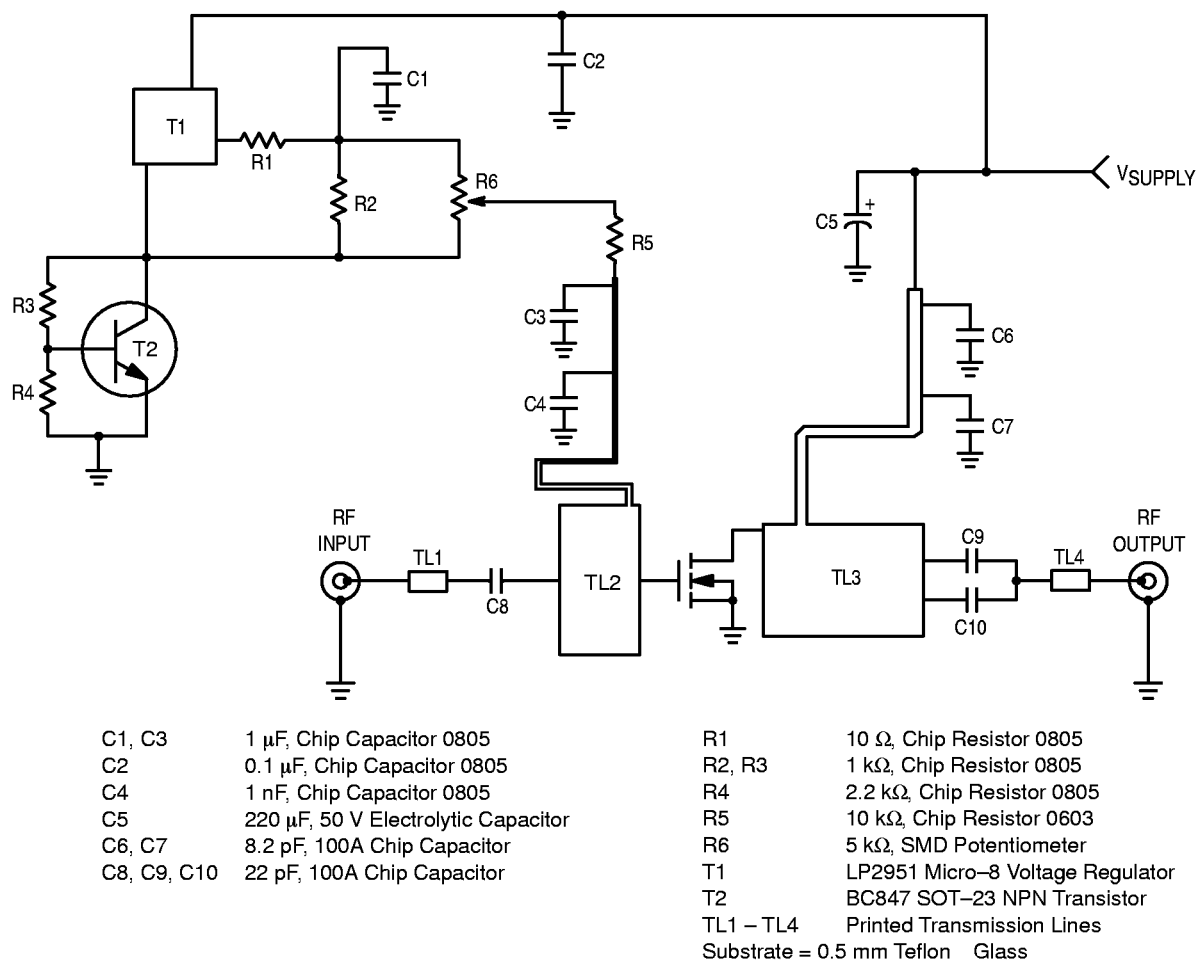


Figure 3. 1.80 – 1.88 GHz Demo Board Schematic

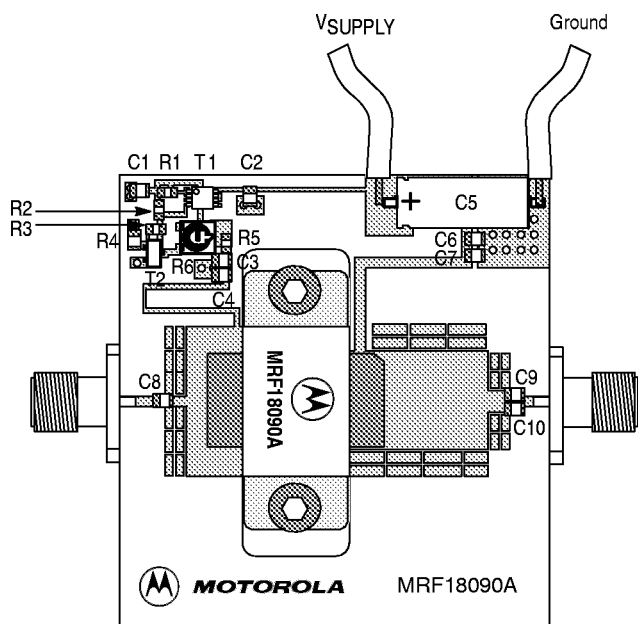


Figure 4. 1.80 – 1.88 GHz Demo Board Component Layout

TYPICAL CHARACTERISTICS

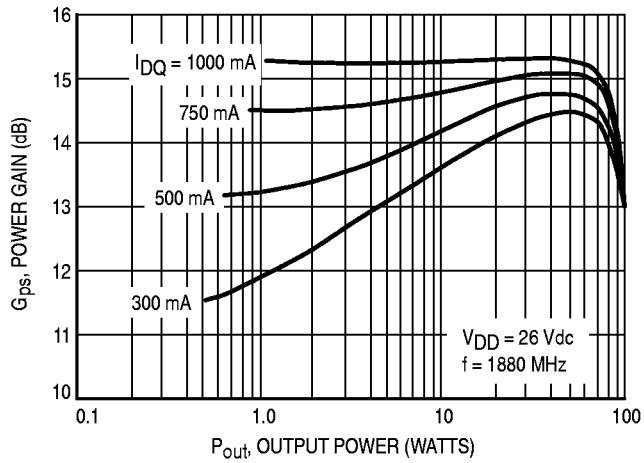


Figure 5. Power Gain versus Output Power

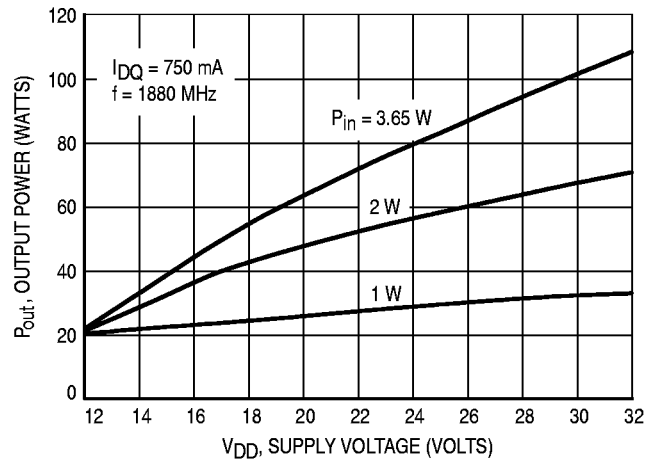


Figure 6. Output Power versus Supply Voltage

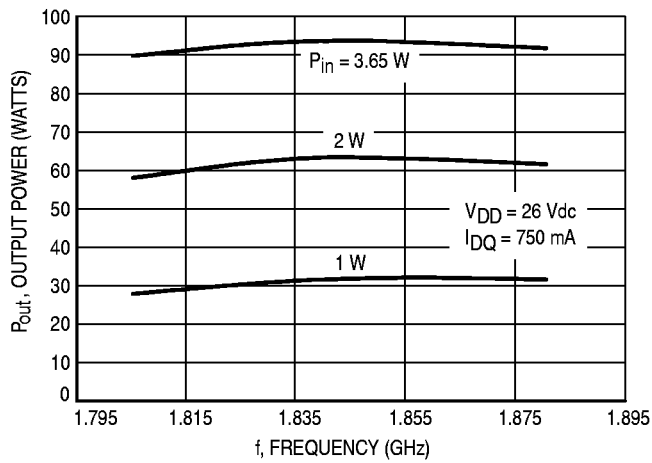


Figure 7. Output Power versus Frequency

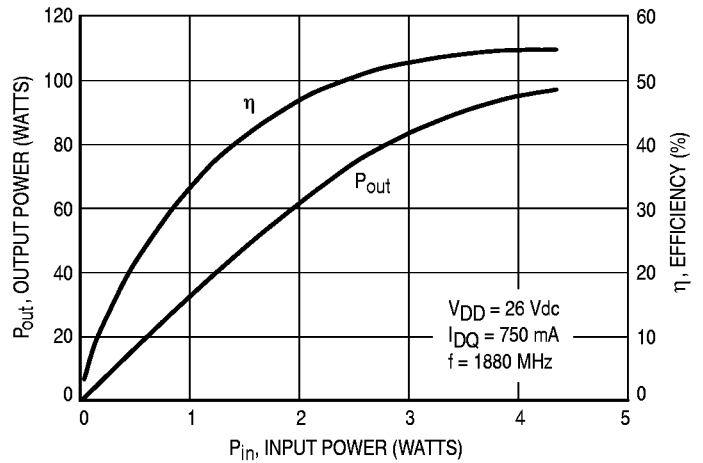


Figure 8. Output Power and Efficiency versus Input Power

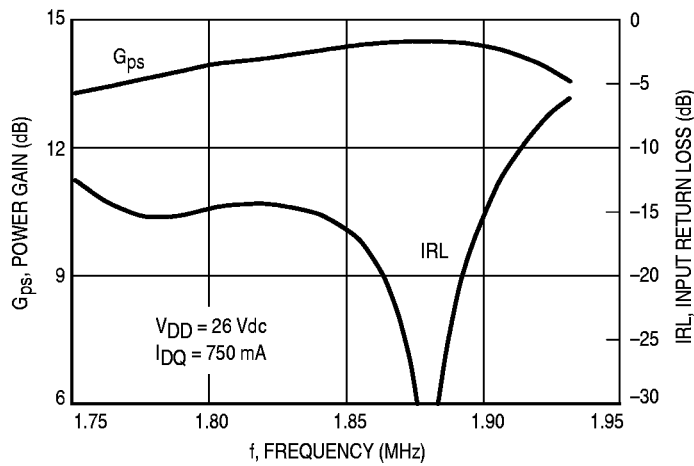


Figure 9. Wideband Gain and IRL (at Small Signal)

$V_{DD} = 26 \text{ V}$, $I_{DQ} = 750 \text{ mA}$, $P_{out} = 90 \text{ Watts (CW)}$

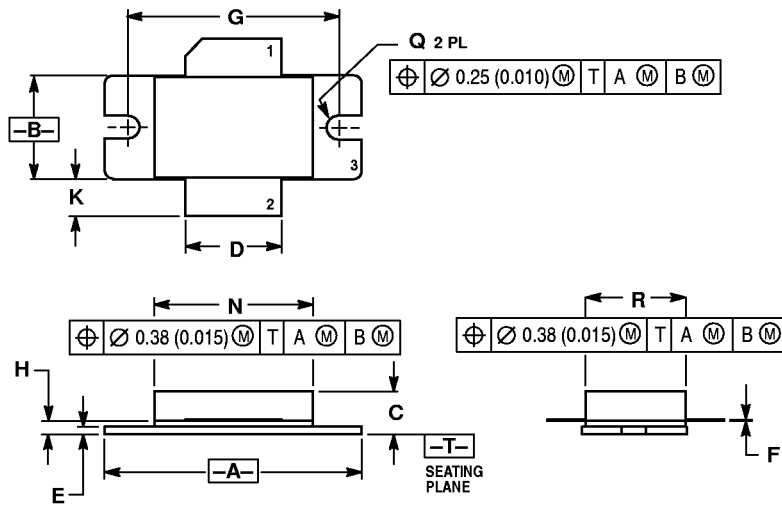
f MHz	Z_{in} Ω	Z_{OL}^* Ω
1805	$1.1 + j5.85$	$1.15 + j2.16$
1880	$1.56 + j6.75$	$1.13 + j2.6$
1930	$2.05 + j8.0$	$1.30 + j2.23$
1990	$2.3 + j7.3$	$0.82 + j2.90$

Z_{in} = Complex conjugate of source impedance.

Z_{OL}^* = Complex conjugate of the optimum load at a given voltage, P1dB, gain, efficiency, bias current and frequency.

Table 1. Large Signal Input and Output Impedance

PACKAGE DIMENSIONS



NOTES:

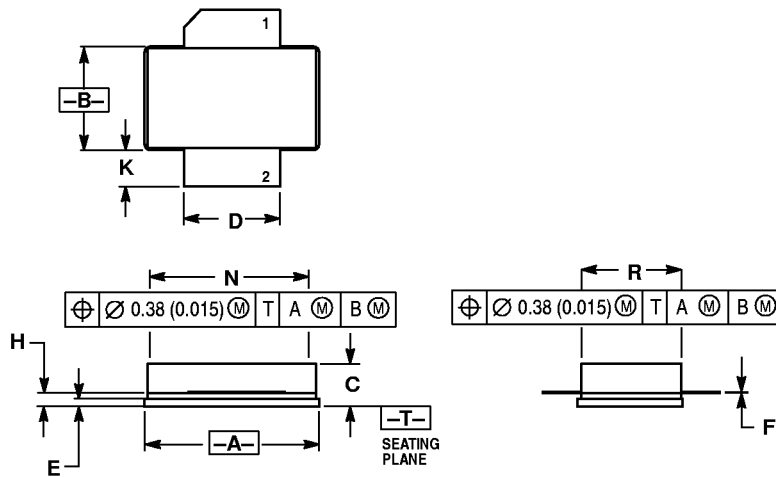
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION H IS MEASURED 0.030" AWAY FROM FLANGE.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.335	1.345	33.91	34.16
B	0.535	0.545	13.6	13.8
C	0.155	0.200	3.94	5.08
D	0.495	0.505	12.57	12.83
E	0.035	0.045	0.89	1.14
F	0.003	0.006	0.08	0.15
G	1.100 BSC		27.94 BSC	
H	0.057	0.067	1.45	1.70
K	0.170	0.210	4.32	5.33
N	0.871	0.889	19.30	22.60
Q	0.118	0.138	3.00	3.51
R	0.515	0.525	13.10	13.30

STYLE 1:

- PIN 1. DRAIN
- GATE
- SOURCE

**CASE 465B-02
ISSUE A**



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION H IS MEASURED 0.030" AWAY FROM FLANGE.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.905	0.915	22.99	23.24
B	0.535	0.545	13.6	13.8
C	0.155	0.200	3.94	5.08
D	0.495	0.505	12.57	12.83
E	0.035	0.045	0.89	1.14
F	0.003	0.006	0.08	0.15
H	0.057	0.067	1.45	1.70
K	0.170	0.210	4.32	5.33
N	0.871	0.889	19.30	22.60
R	0.515	0.525	13.10	13.30

STYLE 1:

- PIN 1. DRAIN
- GATE
- SOURCE

**CASE 465C-01
ISSUE O**